



Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Last Time Buy
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	LCD, POR, PWM, Voltage Detect, WDT
Number of I/O	52
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 10x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2l368cnfp-30

Table 1.2 Programmable I/O Ports Provided for Each Group

Notes:

1. The symbol “ \checkmark ” indicates a programmable I/O port.
 2. The symbol “_” indicates the settings should be made as follows:
 - Set 1 to the corresponding bits in the PDi ($i = 1$ to 3, 5 to 7, and 10 to 13) register.
 - Set 0 to the corresponding bits in the Pi ($i = 1$ to 3, 5 to 7, and 10 to 13) register.
 - Set 0 to the corresponding bits in the P10DDR or P11DDR register.

Table 1.3 LCD Display Function Pins Provided for Each Group

Notes:

- CS.

 1. The symbol “–” indicates there is no LCD display function. Set the corresponding bits in registers LSE1 to LSE3, LSE5 to LSE7 to 0 for these pins.
 2. SEG52 to SEG55 can be used as COM7 to COM4.
The R8C/L35C Group does not have pins SEG52 to SEG55, so 1/8 duty cannot be selected.
 3. The R8C/L35C Group does not have the VL3 pin, so 1/4 bias cannot be selected. When the internal voltage multiplier is used, 1/2 bias cannot also be selected.

1.1.3 Specifications

Tables 1.4 to 1.6 list the Specifications.

Table 1.4 Specifications (1)

Item	Function		Specification	
CPU	Central processing unit		R8C CPU core <ul style="list-style-type: none"> Number of fundamental instructions: 89 Minimum instruction execution time: 50 ns ($f(XIN) = 20$ MHz, VCC = 2.7 to 5.5 V) 200 ns ($f(XIN) = 5$ MHz, VCC = 1.8 to 5.5 V) Multiplier: 16 bits \times 16 bits \rightarrow 32 bits Multiply-accumulate instruction: 16 bits \times 16 bits + 32 bits \rightarrow 32 bits Operating mode: Single-chip mode (address space: 1 Mbyte) 	
Memory	ROM/RAM Data flash		Refer to Tables 1.7 to 1.10 Product Lists .	
Power Supply Voltage Detection	Voltage detection circuit		<ul style="list-style-type: none"> Power-on reset Voltage detection 3 (detection level of voltage detection 0 and voltage detection 1 selectable) 	
I/O Ports	Programmable I/O ports	R8C/L35C Group	<ul style="list-style-type: none"> CMOS I/O ports: 41, selectable pull-up resistor High current drive ports: 5 	
		R8C/L36C Group	<ul style="list-style-type: none"> CMOS I/O ports: 52, selectable pull-up resistor High current drive ports: 8 	
		R8C/L38C Group	<ul style="list-style-type: none"> CMOS I/O ports: 68, selectable pull-up resistor High current drive ports: 8 	
		R8C/L3AC Group	<ul style="list-style-type: none"> CMOS I/O ports: 88, selectable pull-up resistor High current drive ports: 16 	
Clock	Clock generation circuits		4 circuits: XIN clock oscillation circuit XCIN clock oscillation circuit (32 kHz) High-speed on-chip oscillator (with frequency adjustment function) Low-speed on-chip oscillator <ul style="list-style-type: none"> Oscillation stop detection: XIN clock oscillation stop detection function Frequency divider circuit: Division ratio selectable from 1, 2, 4, 8, and 16 Low-power-consumption modes: Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode, power-off mode 	
		Real-time clock (timer RE)		
Interrupts		R8C/L35C Group	<ul style="list-style-type: none"> Number of interrupt vectors: 69 External Interrupt: 9 (INT \times 5, key input \times 4) Priority levels: 7 levels 	
		R8C/L36C Group	<ul style="list-style-type: none"> Number of interrupt vectors: 69 External Interrupt: 12 (INT \times 8, key input \times 4) Priority levels: 7 levels 	
		R8C/L38C Group	<ul style="list-style-type: none"> Number of interrupt vectors: 69 External Interrupt: 16 (INT \times 8, key input \times 8) Priority levels: 7 levels 	
		R8C/L3AC Group	<ul style="list-style-type: none"> Number of interrupt vectors: 69 External Interrupt: 16 (INT \times 8, key input \times 8) Priority levels: 7 levels 	
Watchdog Timer		<ul style="list-style-type: none"> 14 bits \times 1 (with prescaler) Selectable reset start function Selectable low-speed on-chip oscillator for watchdog timer 		
DTC (Data Transfer Controller)		<ul style="list-style-type: none"> 1 channel Activation sources: 38 Transfer modes: 2 (normal mode, repeat mode) 		

Table 1.6 Specifications (3)

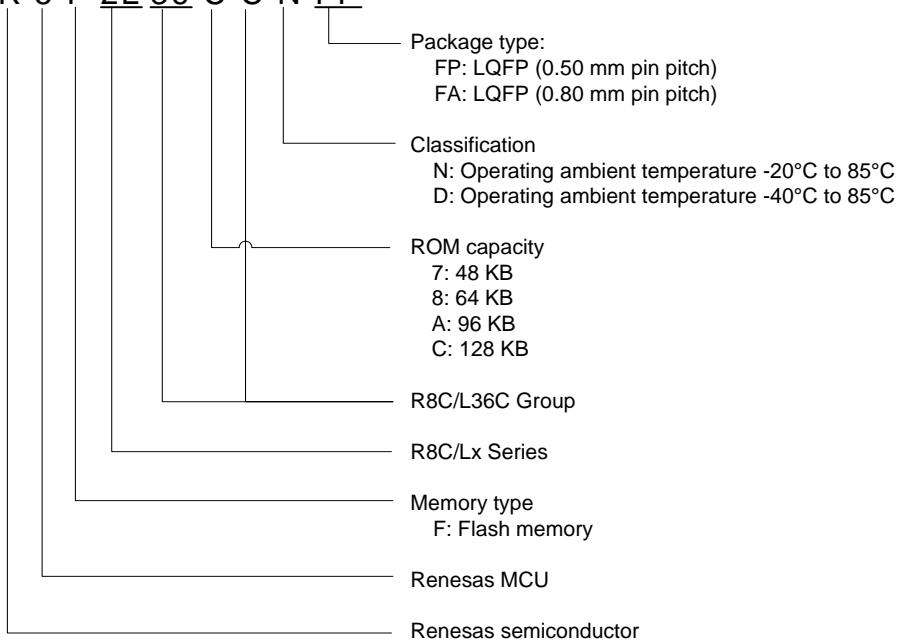
Item	Specification
Flash Memory	<ul style="list-style-type: none"> • Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 10,000 times (data flash) 1,000 times (program ROM) • Program security: ROM code protect, ID code check • On-chip debug function • On-board flash rewrite function • Background operation (BGO) function
Operating Frequency/ Supply Voltage	f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 1.8 to 5.5 V)
Current Consumption	<p>Typ. 7 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 3.6 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 3.5 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) Typ. 2 μA (VCC = 3.0 V, stop mode) Typ. 0.02 μA (VCC = 3.0 V, power-off mode)</p>
Operating Ambient Temperature	-20 to 85°C (N version) -40 to 85°C (D version) ⁽¹⁾

Note:

1. Specify the D version if D version functions are to be used.

Table 1.8 Product List for R8C/L36C Group**Current of Apr 2011**

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F2L367CNFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A	N Version
R5F2L367CNFA	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064GA-A	
R5F2L368CNFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A	
R5F2L368CNFA	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064GA-A	
R5F2L36ACNFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A	
R5F2L36ACNFA	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A	
R5F2L36CCNFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A	
R5F2L36CCNFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A	
R5F2L367CDFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A	D Version
R5F2L367CDFA	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064GA-A	
R5F2L368CDFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A	
R5F2L368CDFA	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064GA-A	
R5F2L36ACDFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A	
R5F2L36ACDFA	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A	
R5F2L36CCDFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A	
R5F2L36CCDFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A	

Part No. R 5 F 2L 36 C C N FP**Figure 1.2 Correspondence of Part No., with Memory Size and Package of R8C/L36C Group**

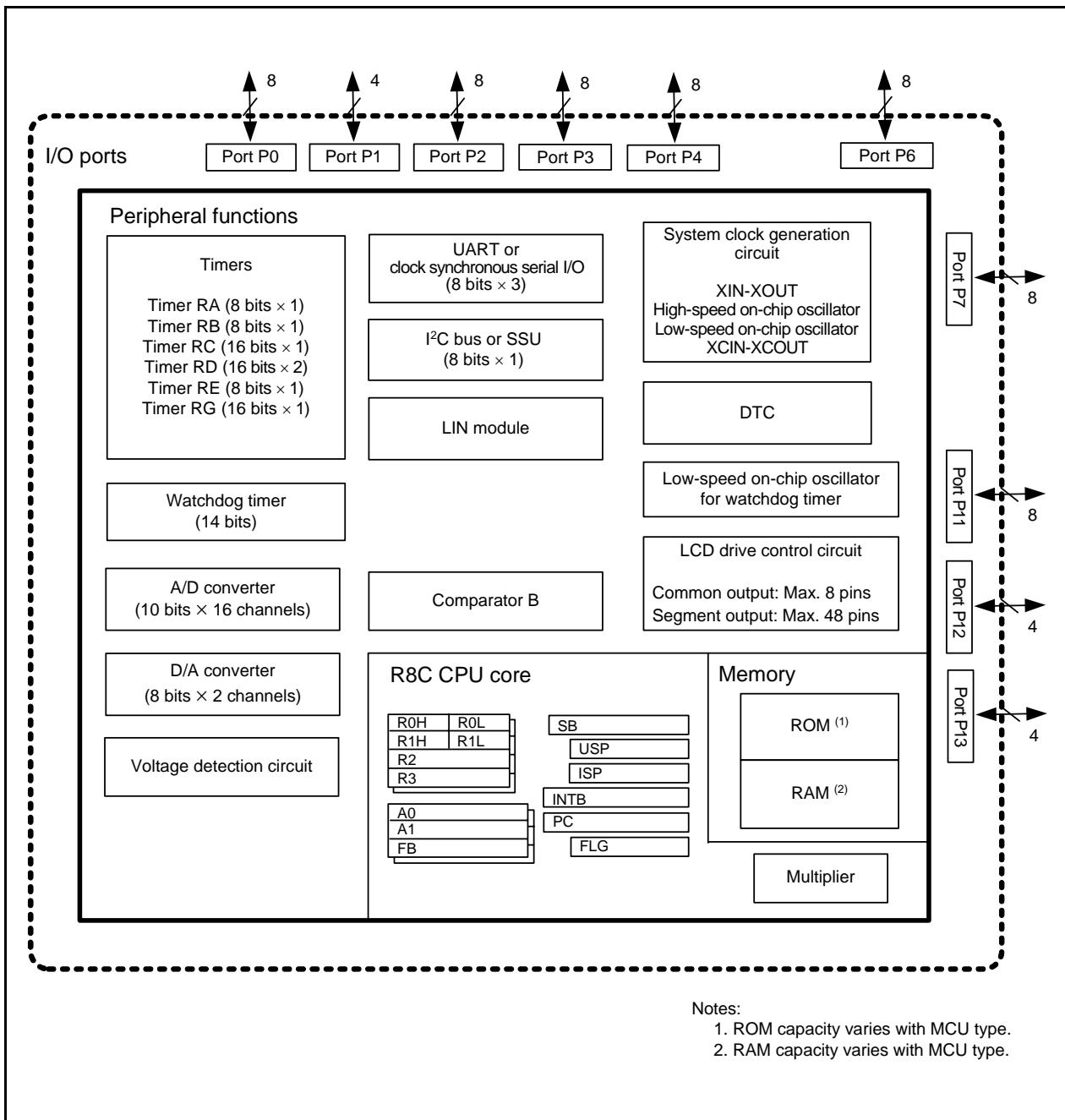


Figure 1.7 Block Diagram of R8C/L38C Group

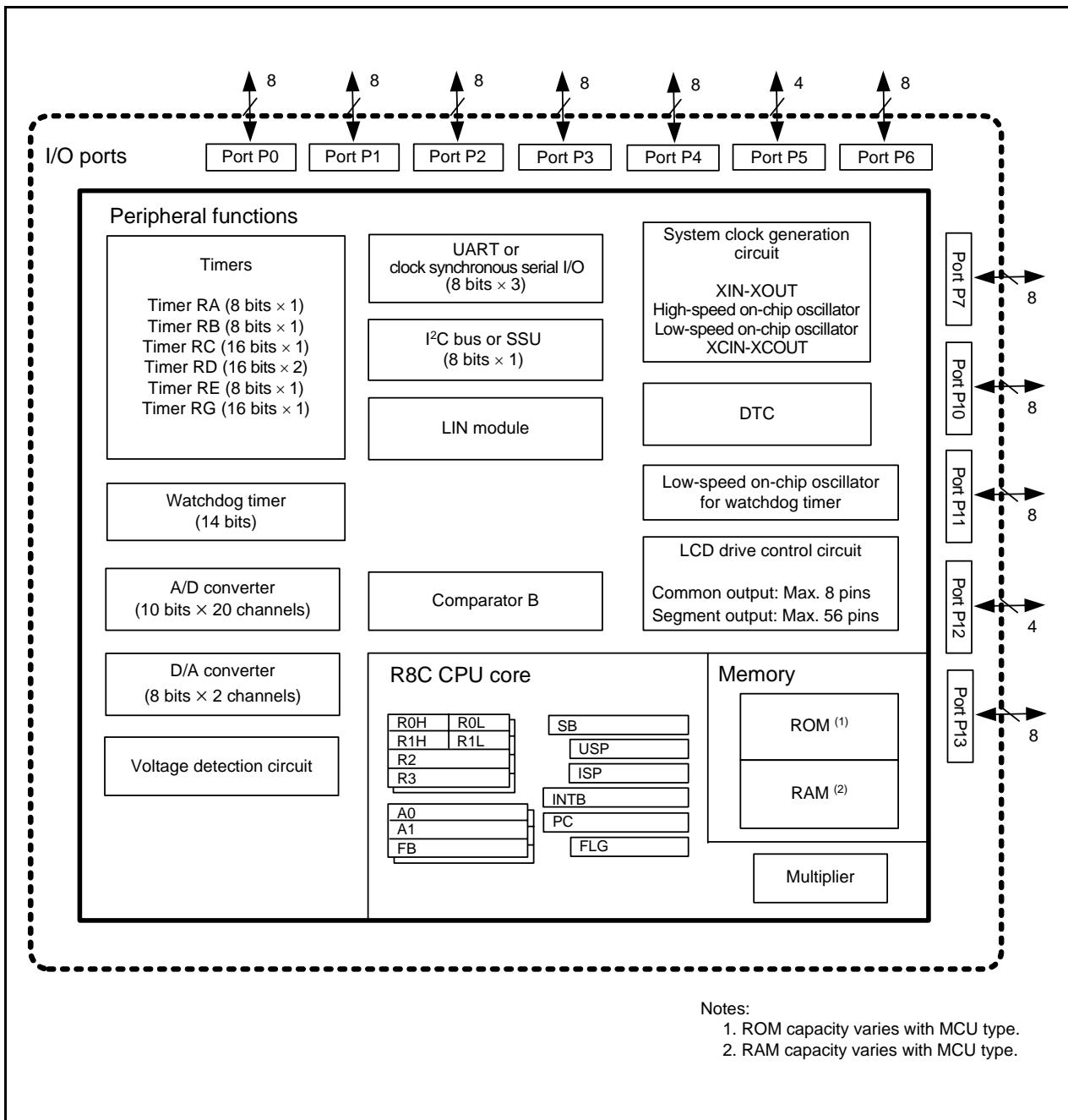
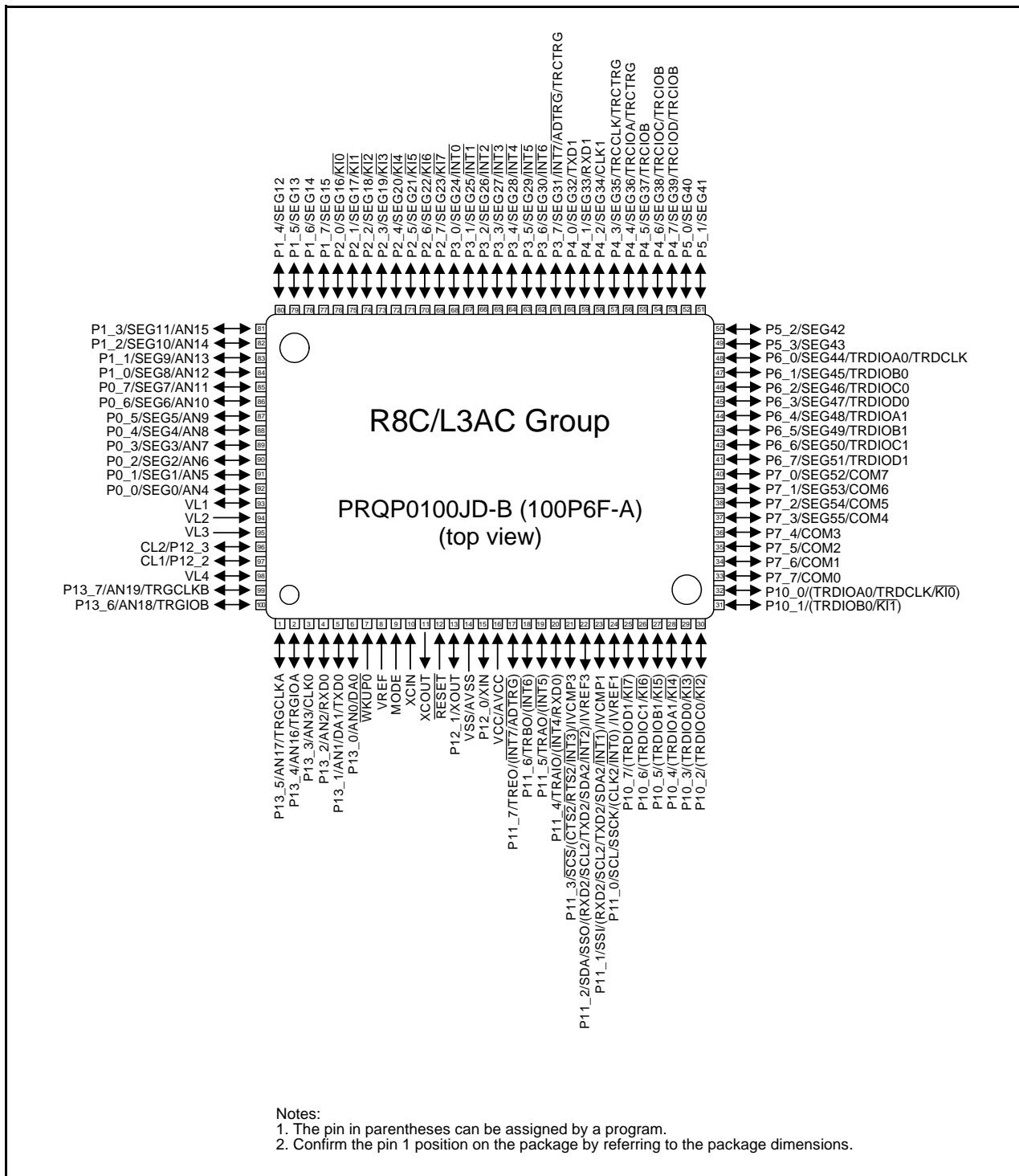


Figure 1.8 Block Diagram of R8C/L3AC Group

**Figure 1.13 Pin Assignment (Top View) of PRQP0100JD-B Package**

1.5 Pin Functions

Tables 1.14 and 1.15 list Pin Functions for R8C/L3AC Group.

Table 1.14 Pin Functions for R8C/L3AC Group (1)

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	–	Apply 1.8 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	–	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	RESET	I	Driving this pin low resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
Power-off mode exit input	WKUP0	I	This pin is provided for input to exit the mode used in power-off mode. Connect to VSS when not using power-off mode.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic oscillator or a crystal oscillator between pins XIN and XOUT. (1) To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XIN clock output	XOUT	O	XIN and XOUT. (1) To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XCIN clock input	XCIN	I	These pins are provided for XCIN clock generation circuit I/O. Connect a crystal oscillator between pins XCIN and XCOUT. (1) To use an external clock, input it to the XCIN pin and leave the XCOUT pin open.
XCIN clock output	XCOUT	O	To use an external clock, input it to the XCIN pin and leave the XCOUT pin open.
INT interrupt input	INT0 to INT7	I	INT interrupt input pins.
Key input interrupt	KI0 to KI7	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRAO	O	Timer RA output pin
Timer RB	TRBO	O	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
	TRCTRG	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIOC, TRCIOD	I/O	Timer RC I/O pins
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDILOC0, TRDILOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O pins
	TRDCLK	I	External clock input pin
Timer RE	TREO	O	Divided clock output pin
Timer RG	TRGCLKA, TRGCLKB	I	Timer RG input pins
	TRGIOA, TRGIOB	I/O	Timer RG I/O pins
Serial interface	CLK0, CLK1, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD1, RXD2	I	Serial data input pins
	TXD0, TXD1, TXD2	O	Serial data output pins
	CTS2	I	Transmission control input pin
	RTS2	O	Reception control output pin
	SCL2	I/O	I ² C mode clock I/O pin
	SDA2	I/O	I ² C mode data I/O pin

I: Input O: Output I/O: Input and output

Note:

- Contact the oscillator manufacturer for oscillation characteristics.

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the starting address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.

4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.16 list SFR Informations and Table 4.17 lists the ID Code Areas and Option Function Select Area. The description offered in this chapter is based on the R8C/L3AC Group.

Table 4.1 SFR Information (1) (1)

Address	Register	Symbol	After Reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	00100000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h	Module Standby Control Register	MSTCR	00h
0009h	System Clock Control Register 3	CM3	00h
000Ah	Protect Register	PRCR	00h
000Bh	Reset Source Determination Register	RSTFR	X _X h (2)
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	X _X h
000Eh	Watchdog Timer Start Register	WDTS	X _X h
000Fh	Watchdog Timer Control Register	WDTC	00111111b
0010h			
0011h			
0012h			
0013h			
0014h			
0015h	High-Speed On-Chip Oscillator Control Register 7	FRA7	When shipping
0016h			
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h 10000000b (3)
001Dh			
001Eh			
001Fh			
0020h	Power-Off Mode Control Register 0	POMCR0	X0000000b
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h	On-Chip Reference Voltage Control Register	OCVREFCR	00h
0027h			
0028h			
0029h	High-Speed On-Chip Oscillator Control Register 4	FRA4	When Shipping
002Ah	High-Speed On-Chip Oscillator Control Register 5	FRA5	When Shipping
002Bh	High-Speed On-Chip Oscillator Control Register 6	FRA6	When Shipping
002Ch			
002Dh			
002Eh			
002Fh	High-Speed On-Chip Oscillator Control Register 3	FRA3	When shipping
0030h	Voltage Monitor Circuit Control Register	CMPA	00h
0031h	Voltage Monitor Circuit Edge Select Register	VCAC	00h
0032h			
0033h	Voltage Detect Register 1	VCA1	00001000b
0034h	Voltage Detect Register 2	VCA2	00h (4) 00100000b (5)
0035h			
0036h	Voltage Detection 1 Level Select Register	VD1LS	00000111b
0037h			
0038h	Voltage Monitor 0 Circuit Control Register	VW0C	1100X010b (4) 1100X011b (5)
0039h	Voltage Monitor 1 Circuit Control Register	VW1C	10001010b

X: Undefined

Notes:

1. Blank spaces are reserved. No access is allowed.
2. The CWR bit in the RSTFR register is set to 0 after power-on, voltage monitor 0 reset, or exit from power-off mode. Hardware reset, software reset, or watchdog timer reset does not affect this bit.
3. The CSPROINI bit in the OFS register is set to 0.
4. The LVDas bit in the OFS register is set to 1.
5. The LVDas bit in the OFS register is set to 0.

Table 4.3 SFR Information (3) (1)

Address	Register	Symbol	After Reset
0080h	DTC Activation Control Register	DTCTL	00h
0081h			
0082h			
0083h			
0084h			
0085h			
0086h			
0087h			
0088h	DTC Activation Enable Register 0	DTCEN0	00h
0089h	DTC Activation Enable Register 1	DTCEN1	00h
008Ah	DTC Activation Enable Register 2	DTCEN2	00h
008Bh	DTC Activation Enable Register 3	DTCEN3	00h
008Ch	DTC Activation Enable Register 4	DTCEN4	00h
008Dh	DTC Activation Enable Register 5	DTCEN5	00h
008Eh	DTC Activation Enable Register 6	DTCEN6	00h
008Fh			
0090h			
0091h			
0092h			
0093h			
0094h			
0095h			
0096h			
0097h			
0098h			
0099h			
009Ah			
009Bh			
009Ch			
009Dh			
009Eh			
009Fh			
00A0h	UART0 Transmit/Receive Mode Register	U0MR	00h
00A1h	UART0 Bit Rate Register	U0BRG	XXh
00A2h	UART0 Transmit Buffer Register	U0TB	XXh XXh
00A3h			
00A4h	UART0 Transmit/Receive Control Register 0	U0C0	00001000b
00A5h	UART0 Transmit/Receive Control Register 1	U0C1	00000010b
00A6h	UART0 Receive Buffer Register	U0RB	XXh XXh
00A7h			
00A8h	UART2 Transmit/Receive Mode Register	U2MR	00h
00A9h	UART2 Bit Rate Register	U2BRG	XXh
00AAh	UART2 Transmit Buffer Register	U2TB	XXh XXh
00ABh			
00ACh	UART2 Transmit/Receive Control Register 0	U2C0	00001000b
00ADh	UART2 Transmit/Receive Control Register 1	U2C1	00000010b
00AEh	UART2 Receive Buffer Register	U2RB	XXh XXh
00AFh			
00B0h	UART2 Digital Filter Function Select Register	URXDF	00h
00B1h			
00B2h			
00B3h			
00B4h			
00B5h			
00B6h			
00B7h			
00B8h			
00B9h			
00BAh			
00BBh	UART2 Special Mode Register 5	U2SMR5	00h
00BCh	UART2 Special Mode Register 4	U2SMR4	00h
00BDh	UART2 Special Mode Register 3	U2SMR3	000X0X0Xb
00BEh	UART2 Special Mode Register 2	U2SMR2	X0000000b
00BFh	UART2 Special Mode Register	U2SMR	X0000000b

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.7 SFR Information (7) (1)

Address	Register	Symbol	After Reset
0180h	Timer RA Pin Select Register	TRASR	00h
0181h	Timer RB/RC Pin Select Register	TRBRCSR	00h
0182h	Timer RC Pin Select Register 0	TRCPSCR0	00h
0183h	Timer RC Pin Select Register 1	TRCPSCR1	00h
0184h	Timer RD Pin Select Register 0	TRDPSR0	00h
0185h	Timer RD Pin Select Register 1	TRDPSR1	00h
0186h			
0187h	Timer RG Pin Select Register	TRGCSR	00h
0188h	UART0 Pin Select Register	U0SR	00h
0189h	UART1 Pin Select Register	U1SR	00h
018Ah	UART2 Pin Select Register 0	U2SR0	00h
018Bh	UART2 Pin Select Register 1	U2SR1	00h
018Ch	SSU/IIC Pin Select Register	SSUIICSR	00h
018Dh	Key Input Pin Select Register	KISR	00h
018Eh	INT Interrupt Input Pin Select Register	INTSR	00h
018Fh	I/O Function Pin Select Register	PINSR	00h
0190h			
0191h			
0192h			
0193h	SS Bit Counter Register	SSBR	1111000b
0194h	SS Transmit Data Register L / IIC bus Transmit Data Register (2)	SSTDR/ICDRT	FFh
0195h	SS Transmit Data Register H (2)	SSTDHR	FFh
0196h	SS Receive Data Register L / IIC bus Receive Data Register (2)	SSRDR/ICDRR	FFh
0197h	SS Receive Data Register H (2)	SSRDRH	FFh
0198h	SS Control Register H / IIC bus Control Register 1 (2)	SSCRH/ICCR1	00h
0199h	SS Control Register L / IIC bus Control Register 2 (2)	SSCRL/ICCR2	0111101b
019Ah	SS Mode Register / IIC bus Mode Register (2)	SSMR/ICMR	00010000b/00011000b
019Bh	SS Enable Register / IIC bus Interrupt Enable Register (2)	SSER/ICIER	00h
019Ch	SS Status Register / IIC bus Status Register (2)	SSSR/ICSR	00h/0000X000b
019Dh	SS Mode Register 2 / Slave Address Register (2)	SSMR2/SAR	00h
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h	Flash Memory Status Register	FST	10000X000b
01B3h			
01B4h	Flash Memory Control Register 0	FMR0	00h
01B5h	Flash Memory Control Register 1	FMR1	00h
01B6h	Flash Memory Control Register 2	FMR2	00h
01B7h			
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			

X: Undefined

Notes:

1. Blank spaces are reserved. No access is allowed.
2. Selectable by the IICSEL bit in the SSUIICSR register.

Table 4.9 SFR Information (9) (1)

Address	Register	Symbol	After Reset
0200h	LCD Control Register	LCR0	00h
0201h	LCD Bias Control Register	LCR1	00h
0202h	LCD Display Control Register	LCR2	X0000000b
0203h	LCD Clock Control Register	LCR3	00h
0204h			
0205h			
0206h	LCD Port Select Register 0	LSE0	00h
0207h	LCD Port Select Register 1	LSE1	00h
0208h	LCD Port Select Register 2	LSE2	00h
0209h	LCD Port Select Register 3	LSE3	00h
020Ah	LCD Port Select Register 4	LSE4	00h
020Bh	LCD Port Select Register 5	LSE5	00h
020Ch	LCD Port Select Register 6	LSE6	00h
020Dh	LCD Port Select Register 7	LSE7	00h
020Eh			
020Fh			
0210h	LCD Display Data Register	LRA0L	XXh
0211h		LRA1L	XXh
0212h		LRA2L	XXh
0213h		LRA3L	XXh
0214h		LRA4L	XXh
0215h		LRA5L	XXh
0216h		LRA6L	XXh
0217h		LRA7L	XXh
0218h		LRA8L	XXh
0219h		LRA9L	XXh
021Ah		LRA10L	XXh
021Bh		LRA11L	XXh
021Ch		LRA12L	XXh
021Dh		LRA13L	XXh
021Eh		LRA14L	XXh
021Fh		LRA15L	XXh
0220h		LRA16L	XXh
0221h		LRA17L	XXh
0222h		LRA18L	XXh
0223h		LRA19L	XXh
0224h		LRA20L	XXh
0225h		LRA21L	XXh
0226h		LRA22L	XXh
0227h		LRA23L	XXh
0228h		LRA24L	XXh
0229h		LRA25L	XXh
022Ah		LRA26L	XXh
022Bh		LRA27L	XXh
022Ch		LRA28L	XXh
022Dh		LRA29L	XXh
022Eh		LRA30L	XXh
022Fh		LRA31L	XXh
0230h		LRA32L	XXh
0231h		LRA33L	XXh
0232h		LRA34L	XXh
0233h		LRA35L	XXh
0234h		LRA36L	XXh
0235h		LRA37L	XXh
0236h		LRA38L	XXh
0237h		LRA39L	XXh
0238h		LRA40L	XXh
0239h		LRA41L	XXh
023Ah		LRA42L	XXh
023Bh		LRA43L	XXh
023Ch		LRA44L	XXh
023Dh		LRA45L	XXh
023Eh		LRA46L	XXh
023Fh		LRA47L	XXh

X: Undefined

Note:

- Blank spaces are reserved. No access is allowed.

Table 4.10 SFR Information (10)⁽¹⁾

Address	Register	Symbol	After Reset
0240h	LCD Display Data Register	LRA48L	XXh
0241h		LRA49L	XXh
0242h		LRA50L	XXh
0243h		LRA51L	XXh
0244h		LRA52L	XXh
0245h		LRA53L	XXh
0246h		LRA54L	XXh
0247h		LRA55L	XXh
0248h			
0249h			
024Ah			
024Bh			
024Ch			
024Dh			
024Eh			
024Fh			
0250h			
0251h			
0252h			
0253h			
0254h			
0255h			
0256h			
0257h			
0258h			
0259h			
025Ah			
025Bh			
025Ch			
025Dh			
025Eh			
025Fh			
0260h			
0261h			
0262h			
0263h			
0264h			
0265h			
0266h			
0267h			
0268h			
0269h			
026Ah			
026Bh			
026Ch			
026Dh			
026Eh			
026Fh			
0270h	LCD Display Control Data Register	LRA0H	XXh
0271h		LRA1H	XXh
0272h		LRA2H	XXh
0273h		LRA3H	XXh
0274h		LRA4H	XXh
0275h		LRA5H	XXh
0276h		LRA6H	XXh
0277h		LRA7H	XXh
0278h		LRA8H	XXh
0279h		LRA9H	XXh
027Ah		LRA10H	XXh
027Bh		LRA11H	XXh
027Ch		LRA12H	XXh
027Dh		LRA13H	XXh
027Eh		LRA14H	XXh
027Fh		LRA15H	XXh

X: Undefined

Note:

- Blank spaces are reserved. No access is allowed.

Table 4.12 SFR Information (12)⁽¹⁾

Address	Register	Symbol	After Reset
02C0h			
02C1h			
02C2h			
02C3h			
02C4h			
02C5h			
02C6h			
02C7h			
02C8h			
02C9h			
02CAh			
02CBh			
02CCh			
02CDh			
02CEh			
02CFh			
02D0h			
02D1h			
02D2h			
02D3h			
02D4h			
02D5h			
02D6h			
02D7h			
02D8h			
02D9h			
02DAh			
02DBh			
02DCh			
02DDh			
02DEh			
02DFh			
02E0h			
02E1h			
02E2h			
02E3h			
02E4h			
02E5h			
02E6h			
02E7h			
02E8h			
02E9h			
02EAh			
02EBh			
02EC _h			
02EDh			
02EEh			
02EFh			
02F0h			
02F1h			
02F2h			
02F3h			
02F4h			
02F5h			
02F6h			
02F7h			
02F8h			
02F9h			
02FAh			
02FBh			
02FC _h			
02FDh			
02FEh			
02FFh			

X: Undefined

Note:

- Blank spaces are reserved. No access is allowed.

**Table 5.6 Flash Memory (Program ROM) Characteristics
(V_{CC} = 2.7 to 5.5 V and T_{OPR} = 0 to 60°C, unless otherwise specified.)**

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		1,000 (2)	—	—	times
—	Byte program time		—	80	500	μs
—	Block erase time		—	0.3	—	s
td(SR-SUS)	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	ms
—	Time from suspend until erase restart		—	—	30+CPU clock × 1 cycle	μs
td(CMDRST-READY)	Time from when command is forcibly terminated until reading is enabled		—	—	30+CPU clock × 1 cycle	μs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		0	—	60	°C
—	Data hold time (6)	Ambient temperature = 55°C	20	—	—	year

Notes:

1. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.10 Voltage Detection 2 Circuit Characteristics
(V_{CC} = 1.8 to 5.5 V and T_{OPR} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{DET2}	Voltage detection level V _{DET2_0}	At the falling of V _{CC}	3.70	4.00	4.30	V
—	Hysteresis width at the rising of V _{CC} in voltage detection 2 circuit		—	0.10	—	V
—	Voltage detection 2 circuit response time ⁽¹⁾	At the falling of V _{CC} from 5 V to (V _{DET2_0} - 0.1) V	—	20	150	μs
—	Voltage detection circuit self power consumption	VCA27 = 1, V _{CC} = 5.0 V	—	1.7	—	μA
t _{D(E-A)}	Waiting time until voltage detection circuit operation starts ⁽²⁾		—	—	100	μs

Notes:

1. Time until the voltage monitor 2 interrupt request is generated after the voltage passes V_{DET2}.
2. Necessary time until the voltage detection circuit operates after setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.

Table 5.11 Power-on Reset Circuit Characteristics ⁽¹⁾
(T_{OPR} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _{RH}	External power V _{CC} rise gradient		0	—	50000	mV/msec

Note:

1. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS register to 0.

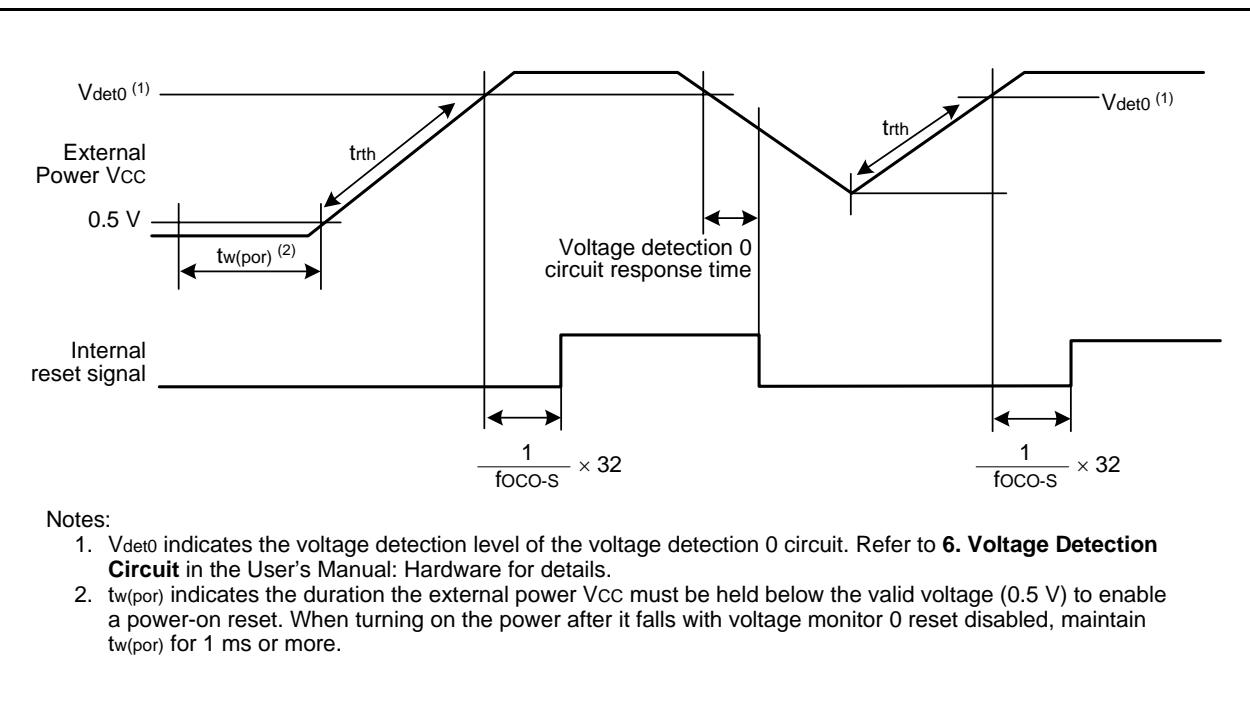


Figure 5.3 Power-on Reset Circuit Characteristics

**Table 5.20 DC Characteristics (4) [2.7 V ≤ Vcc < 4.0 V]
(Topr = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)**

Symbol	Parameter	Condition							Standard			Unit		
		Oscillation Circuit		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other		Min.	Typ. (3)	Max.		
		XIN (2)	XCIN	High-Speed (fOCO-F)	Low-Speed									
Icc	Power supply current (1)	High-speed clock mode	20 MHz	Off	Off	125 kHz	No division	—		—	7.0	14.5	mA	
			10 MHz	Off	Off	125 kHz	No division	—		—	3.6	10	mA	
			20 MHz	Off	Off	125 kHz	Divide-by-8	—		—	3.0	—	mA	
			10 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.5	—	mA	
		High-speed on-chip oscillator mode	Off	Off	20 MHz	125 kHz	No division	—		—	7.0	14.5	mA	
			Off	Off	20 MHz	125 kHz	Divide-by-8	—		—	3.0	—	mA	
			Off	Off	10 MHz	125 kHz	No division	—		—	4.0	—	mA	
			Off	Off	10 MHz	125 kHz	Divide-by-8	—		—	1.7	—	mA	
			Off	Off	4 MHz	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRD = 1 MSTTRC = 1 MSTTRG = 1	—		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 VCA20 = 0	—		—	85	390	μA
			Off	32 kHz	Off	Off	No division	FMR27 = 1 VCA20 = 0	—		—	90	400	μA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMSTP = 1 VCA20 = 0	Flash memory off Program operation on RAM		—	50	—	μA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1	While a WAIT instruction is executed Peripheral clock operation		—	15	90	μA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off		—	5	80	μA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 0	While a WAIT instruction is executed LCD drive control circuit (4) When external division resistors are used Peripheral clock off Timer RE operation in real-time clock mode	—	5	—	μA	
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	LCD drive control circuit (5) When the internal voltage multiplier is used	—	11	—	μA	
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode	—	3.5	—	μA	
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM10 = 1	Topr = 25°C Peripheral clock off	—	2	5.0	μA	
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM10 = 1	Topr = 85°C Peripheral clock off	—	13.0	—	μA	
		Power-off mode	Off	Off	Off	Off	—	—	Topr = 25°C	—	0.02	0.2	μA	
			Off	Off	Off	Off	—	—	Topr = 85°C	—	0.3	—	μA	

Notes:

1. Vcc = 2.7 V to 4.0 V, single chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. Vcc = 3.0 V
4. VLCD = Vcc, external division resistors are used for VL4 to VL1, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open. The standard value does not include the current that flows through external division resistors.
5. The internal voltage multiplier is used, bits LVLS3 to LVLS0 in the LCR1 register = 1011b, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open.

Table 5.24 Timing Requirements of I²C bus Interface (1)
(V_{CC} = 1.8 to 5.5 V, V_{SS} = 0 V, and T_{OPR} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
tsCL	SCL input cycle time		12tCYC + 600 (1)	—	—	ns
tsCLH	SCL input "H" width		3tCYC + 300 (1)	—	—	ns
tsCLL	SCL input "L" width		5tCYC + 500 (1)	—	—	ns
tsf	SCL, SDA input fall time		—	—	300	ns
tSP	SCL, SDA input spike pulse rejection time		—	—	1tCYC (1)	ns
tBUF	SDA input bus-free time		5tCYC (1)	—	—	ns
tSTAH	Start condition input hold time		3tCYC (1)	—	—	ns
tSTAS	Retransmit start condition input setup time		3tCYC (1)	—	—	ns
tSTOP	Stop condition input setup time		3tCYC (1)	—	—	ns
tSDAS	Data input setup time		1tCYC + 40 (1)	—	—	ns
tSDAH	Data input hold time		10	—	—	ns

Note:

1. 1tCYC = 1/f₁(s)

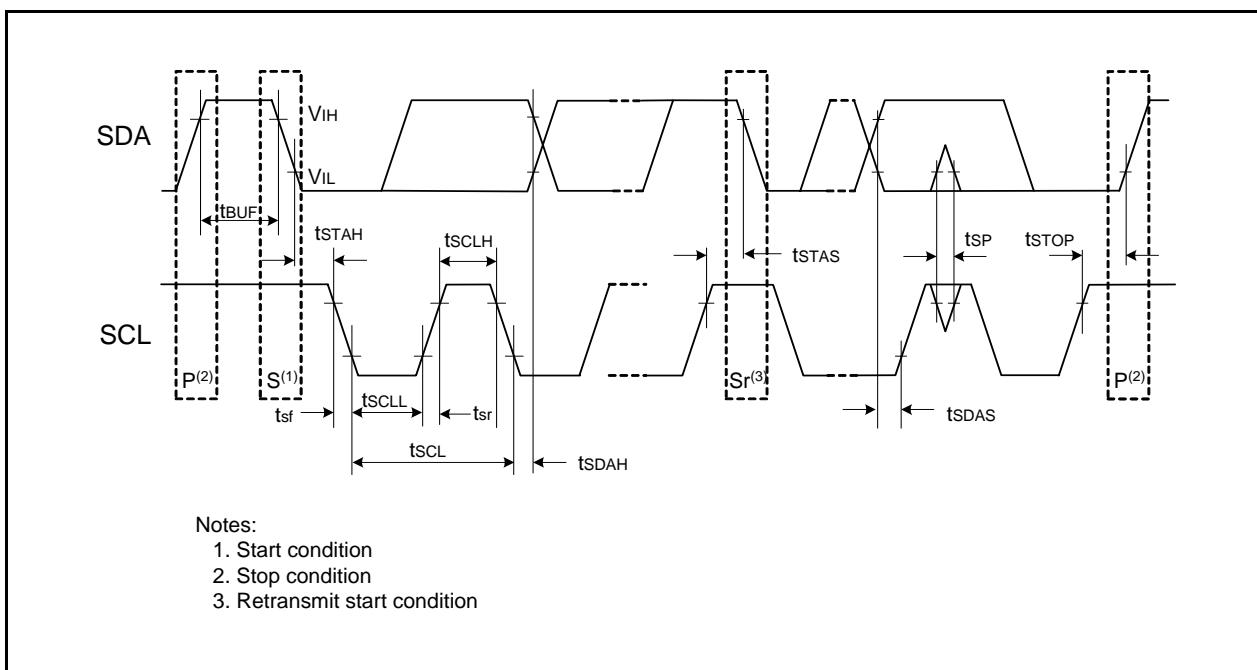
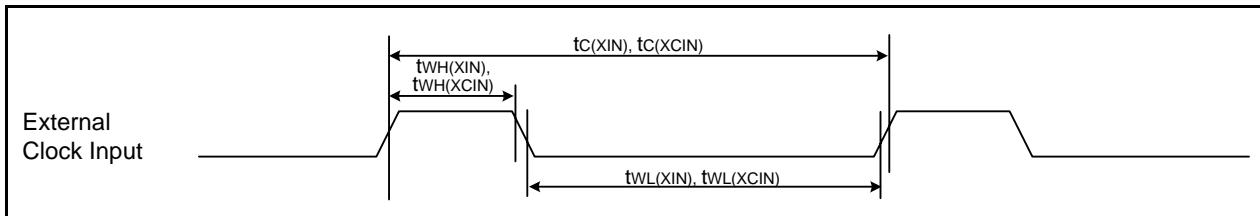


Figure 5.7 I/O Timing of I²C bus Interface

Table 5.25 External Clock Input (XIN, XCIN)

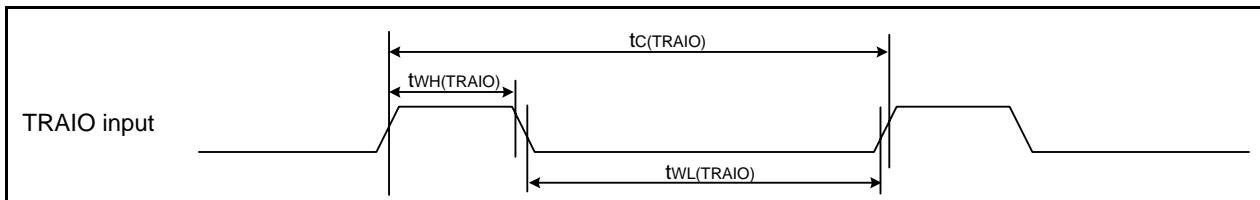
($V_{CC} = 1.8$ to 5.5 V, $V_{SS} = 0$ V, and $T_{OPR} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Standard						Unit	
		$V_{CC} = 2.2$ V, $T_{OPR} = 25^\circ\text{C}$		$V_{CC} = 3$ V, $T_{OPR} = 25^\circ\text{C}$		$V_{CC} = 5$ V, $T_{OPR} = 25^\circ\text{C}$			
		Min.	Max.	Min.	Max.	Min.	Max.		
$t_C(XIN)$	XIN input cycle time	200	—	50	—	50	—	ns	
$t_{WH}(XIN)$	XIN input "H" width	90	—	24	—	24	—	ns	
$t_{WL}(XIN)$	XIN input "L" width	90	—	24	—	24	—	ns	
$t_C(XCIN)$	XCIN input cycle time	14	—	14	—	14	—	μs	
$t_{WH}(XCIN)$	XCIN input "H" width	7	—	7	—	7	—	μs	
$t_{WL}(XCIN)$	XCIN input "L" width	7	—	7	—	7	—	μs	

**Figure 5.8 External Clock Input Timing Diagram****Table 5.26 Timing Requirements of TRAIO**

($V_{CC} = 1.8$ to 5.5 V, $V_{SS} = 0$ V and $T_{OPR} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Standard						Unit	
		$V_{CC} = 2.2$ V, $T_{OPR} = 25^\circ\text{C}$		$V_{CC} = 3$ V, $T_{OPR} = 25^\circ\text{C}$		$V_{CC} = 5$ V, $T_{OPR} = 25^\circ\text{C}$			
		Min.	Max.	Min.	Max.	Min.	Max.		
$t_C(TRAIO)$	TRAIO input cycle time	500	—	300	—	100	—	ns	
$t_{WH}(TRAIO)$	TRAIO input "H" width	200	—	120	—	40	—	ns	
$t_{WL}(TRAIO)$	TRAIO input "L" width	200	—	120	—	40	—	ns	

**Figure 5.9 Input Timing of TRAIO**